TEXAS INSTRUMENTS

SN54AHC16244, SN74AHC16244

SCLS327H – MARCH 1996 – REVISED OCTOBER 2014

SNx4AHC16244 16-Bit Buffers/Drivers With 3-State Outputs

1 Features

- Members of the Texas Instruments *Widebus*™ Family
- *EPIC*™ (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V_{CC}
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

2 Applications

- Motor Drives
- Wireless Infrastructures
- Health and Fitness Wearables
- Telecom Infrastructures
- Electronic Points of Sale

3 Description

The SNx4AHC16244 devices are 16-bit buffers and line drivers designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

Device Information[1]

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SNx4AHC16244	SSOP (48)	15.80 mm × 7.50 mm
	TSSOP (48)	12.50 mm 6.10 mm
	TVSOP (48)	9.70 mm 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.
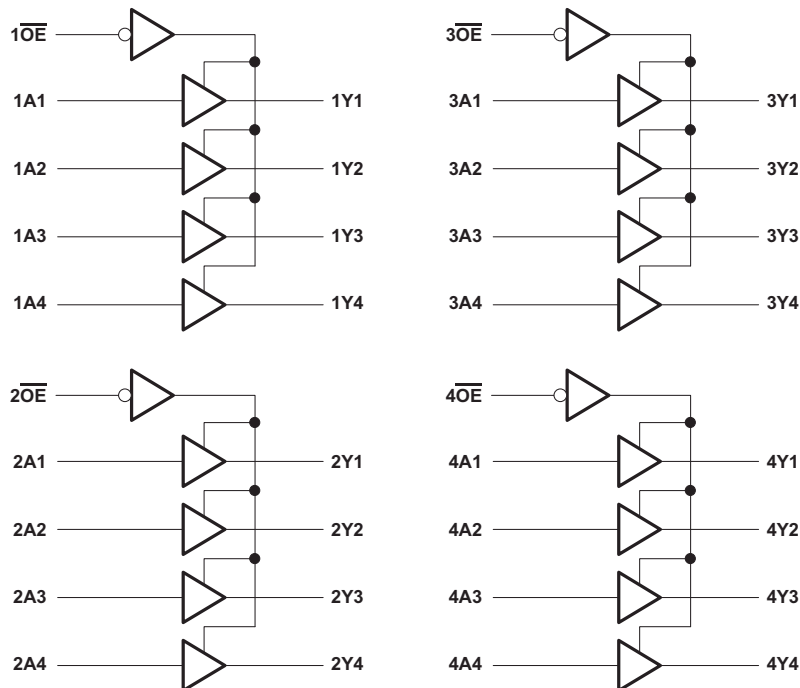
4 Simplified Schematic

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6 Pin Configuration and Functions

SN54AHC16244 . . . WD PACKAGE
SN74AHC16244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)

1$\overline{\text{OE}}$	1	48	2$\overline{\text{OE}}$
1Y1	2	47	1A1
1Y2	3	46	1A2
GND	4	45	GND
1Y3	5	44	1A3
1Y4	6	43	1A4
V_{CC}	7	42	V_{CC}
2Y1	8	41	2A1
2Y2	9	40	2A2
GND	10	39	GND
2Y3	11	38	2A3
2Y4	12	37	2A4
3Y1	13	36	3A1
3Y2	14	35	3A2
GND	15	34	GND
3Y3	16	33	3A3
3Y4	17	32	3A4
V_{CC}	18	31	V_{CC}
4Y1	19	30	4A1
4Y2	20	29	4A2
GND	21	28	GND
4Y3	22	27	4A3
4Y4	23	26	4A4
4$\overline{\text{OE}}$	24	25	3$\overline{\text{OE}}$
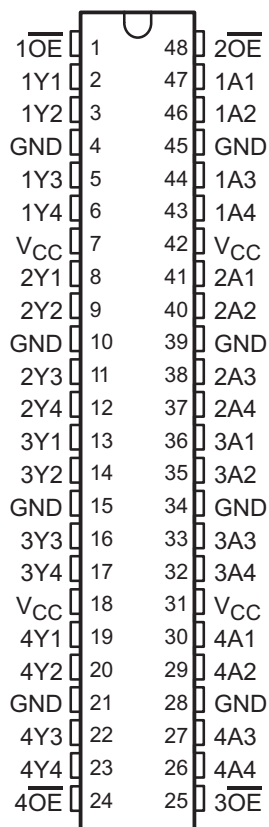
Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	1$\overline{\text{OE}}$	I	Output Enable 1
2	1Y1	O	1Y1 Output
3	1Y2	O	1Y2 Output
4	GND	—	Ground Pin
5	1Y3	O	1Y3 Output
6	1Y4	O	1Y4 Output
7	V_{CC}	—	Power Pin
8	2Y1	O	2Y1 Output
9	2Y2	O	2Y2 Output
10	GND	—	Ground Pin
11	2Y3	O	2Y3 Output
12	2Y4	O	2Y4 Output
13	3Y1	O	3Y1 Output
14	3Y2	O	3Y2 Output
15	GND	—	Ground Pin
16	3Y3	O	3Y3 Output
17	3Y4	O	3Y4 Output
18	V_{CC}	—	Power Pin

Product Folder Links: *SN54AHC16244 SN74AHC16244*

Pin Functions (continued)

PIN		I/O	DESCRIPTION
NO.	NAME		
19	4Y1	O	4Y1 Output
20	4Y2	O	4Y2 Output
21	GND	—	Ground Pin
22	4Y3	O	4Y3 Output
23	4Y4	O	4Y4 Output
24	4$\overline{\text{OE}}$	I	Output Enable 4
25	3$\overline{\text{OE}}$	I	Output Enable 3
26	4A4	I	4A4 Input
27	4A3	I	4A3 Input
28	GND	—	Ground Pin
29	4A2	I	4A2 Input
30	4A1	I	4A1 Input
31	V_{CC}	—	Power Pin
32	3A4	I	3A4 Input
33	3A3	I	3A3 Input
34	GND	—	Ground Pin
35	3A2	I	3A2 Input
36	3A1	I	3A1 Input
37	2A4	I	2A4 Input
38	2A3	I	2A3 Input
39	GND	—	Ground Pin
40	2A2	I	2A2 Input
41	2A1	I	2A1 Input
42	V_{CC}	—	Power Pin
43	1A4	I	1A4 Input
44	1A3	I	1A3 Input
45	GND	—	Ground Pin
46	1A2	I	1A2 Input
47	1A1	I	1A1 Input
48	2$\overline{\text{OE}}$	I	Output Enable 2

Product Folder Links: *SN54AHC16244 SN74AHC16244*

7 Specifications

7.1 Absolute Maximum Ratings[(1)]

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		−0.5	7	V
V_I	Input voltage range[(2)]		−0.5	7	V
V_O	Output voltage range[(2)]		−0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	$V_I < 0$		−20	mA
I_{OK}	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$		±20	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±75	mA

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

7.2 Handling Ratings

			MIN	MAX	UNIT
T_{stg}	Storage temperature range		−65	150	°C
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins[(1)]	0	2000	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)[(1)]

			SN54AHC16244[(2)]		SN74AHC16244		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 3 V	2.1		2.1		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 3 V		0.9		0.9	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		−50		−50	µA
		V_{CC} = 3.3 V ± 0.3 V		−4		−4	mA
		V_{CC} = 5 V ± 0.5 V		−8		−8	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	µA
		V_{CC} = 3.3 V ± 0.3 V		4		4	mA
		V_{CC} = 5 V ± 0.5 V		8		8	
$\Delta t / \Delta v$	Input transition rise or fall rate	V_{CC} = 3.3 V ± 0.3 V		100		100	ns/V
		V_{CC} = 5 V ± 0.5 V		20		20	
T_A	Operating free-air temperature		−55	125	−40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

(2) Product Preview

Product Folder Links: *SN54AHC16244 SN74AHC16244*

7.4 Thermal Information

THERMAL METRIC[1]		SN74AHC16244			UNIT
		DGV	DL	DGG	
		48 PINS	48 PINS	48 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	83.5	64.6	72.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	35.7	34.5	26.8	
$R_{\theta JB}$	Junction-to-board thermal resistance	46.6	36.4	39.4	
ψ_{JT}	Junction-to-top characterization parameter	4.3	11.1	2.6	
ψ_{JB}	Junction-to-board characterization parameter	46.0	36.1	39.1	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25°C$			SN54AHC16244[1]		SN74AHC16244		−40°C to 125°C SN74AHC16244		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$I_{OH} = -50\ \mu A$	2 V	1.9	2		1.9		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		4.4		
	$I_{OH} = -4\ mA$	3 V	2.58			2.48		2.48		2.48		
	$I_{OH} = -8\ mA$	4.5 V	3.94			3.8		3.8		3.8		
V_{OL}	$I_{OL} = 50\ \mu A$	2 V			0.1		0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1		0.1	
	$I_{OL} = 4\ mA$	3 V			0.36		0.5		0.44		0.44	
	$I_{OL} = 8\ mA$	4.5 V			0.36		0.5		0.44		0.44	
I_I	$V_I = V_{CC}$ or GND	0 V to 5.5 V			±0.1		±1 [2]		±1		±1	μA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±2.5		±2.5		±2.5	μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40		40	μA
C_i	$V_I = V_{CC}$ or GND	5 V		2	10		10		10		10	pF
C_o	$V_O = V_{CC}$ or GND	5 V		3.5									pF

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0$ V.

Product Folder Links: *SN54AHC16244   SN74AHC16244*

7.6 Switching Characteristics, V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHC16244[1]		SN74AHC16244		T_A = −40°C to 125°C SN74AHC16244		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 15 pF		5.8[2]	8.4[2]	1[2]	10[2]	1	10	1	11	ns
t_{PHL}					5.8[2]	8.4[2]	1[2]	10[2]	1	10	1	11	
t_{PZH}	$\overline{OE}$	Y	C_L = 15 pF		6.6[2]	10.6[2]	1[2]	12.5[2]	1	12.5	1	13.5	ns
t_{PZL}					6.6[2]	10.6[2]	1[2]	12.5[2]	1	12.5	1	13.5	
t_{PHZ}	$\overline{OE}$	Y	C_L = 15 pF		5[2]	11.5[2]	1[2]	12.5[2]	1	12.5	1	13.5	ns
t_{PLZ}					5[2]	11.5[2]	1[2]	12.5[2]	1	12.5	1	13.5	
t_{PLH}	A	Y	C_L = 50 pF		8.3	11.9	1	13.5	1	13.5	1	14.5	ns
t_{PHL}					8.3	11.9	1	13.5	1	13.5	1	14.5	
t_{PZH}	$\overline{OE}$	Y	C_L = 50 pF		9.1	14.1	1	16	1	16	1	17	ns
t_{PZL}					9.1	14.1	1	16	1	16	1	17	
t_{PHZ}	$\overline{OE}$	Y	C_L = 50 pF		10.3	14	1	16	1	16	1	17	ns
t_{PLZ}					10.3	14	1	16	1	16	1	17	
$t_{sk(o)}$			C_L = 50 pF			1.5[3]				1.5		1.5	ns

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.
(3) On products compliant to MIL-PRF-38535, this parameter does not apply.

7.7 Switching Characteristics, V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54AHC16244[1]		SN74AHC16244		T_A = −40°C to 125°C SN74AHC16244		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	C_L = 15 pF		3.9[2]	6[2]	1[2]	7[2]	1	6.5	1	7	ns
t_{PHL}					3.9[2]	6[2]	1[2]	7[2]	1	6.5	1	7	
t_{PZH}	$\overline{OE}$	Y	C_L = 15 pF		4.7[2]	7.3[2]	1[2]	8.5[2]	1	8.5	1	9.5	ns
t_{PZL}					4.7[2]	7.3[2]	1[2]	8.5[2]	1	8.5	1	9.5	
t_{PHZ}	$\overline{OE}$	Y	C_L = 15 pF		5[2]	7.2[2]	1[2]	8.5[2]	1	8.5	1	9	ns
t_{PLZ}					5[2]	7.2[2]	1[2]	8.5[2]	1	8.5	1	9	
t_{PLH}	A	Y	C_L = 50 pF		5.4	8	1	9	1	8.5	1	9	ns
t_{PHL}					5.4	8	1	9	1	8.5	1	9	
t_{PZH}	$\overline{OE}$	Y	C_L = 50 pF		6.2	9.3	1	10.5	1	10.5	1	11.5	ns
t_{PZL}					6.2	9.3	1	10.5	1	10.5	1	11.5	
t_{PHZ}	$\overline{OE}$	Y	C_L = 50 pF		6.7	9.2	1	10.5	1	10.5	1	11	ns
t_{PLZ}					6.7	9.2	1	10.5	1	10.5	1	11	
$t_{sk(o)}$			C_L = 50 pF			1[3]				1		1	ns

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.
(3) On products compliant to MIL-PRF-38535, this parameter does not apply.

7.8 Noise Characteristics

V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C[1]

PARAMETER		SN74AHC16244			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.5	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.2	−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		4.8		V
$V_{IH(D)}$	High-level dynamic input voltage	3.5			V
$V_{IL(D)}$	Low-level dynamic input voltage			1.5	V

(1) Characteristics are for surface-mount packages only.

Product Folder Links: *SN54AHC16244 SN74AHC16244*

7.9 Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	10.5	pF

7.10 Typical Characteristics

Figure 1. TPD vs Temperature (V_{CC} = 5 V)

Figure 2. TPD vs V_{CC} (T_A = 25°C)

Product Folder Links: *SN54AHC16244 SN74AHC16244*
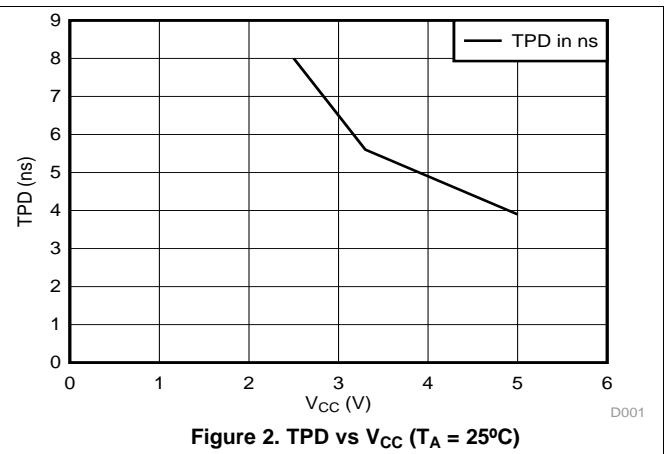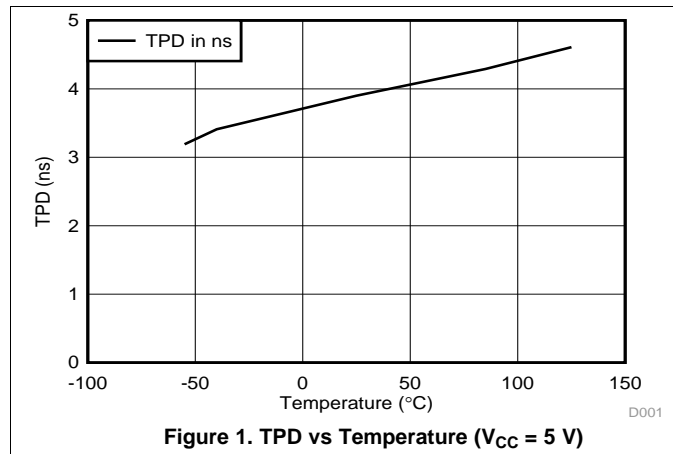
8 Parameter Measurement Information

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

**LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS**

**LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS**

**VOLTAGE WAVEFORMS
PULSE DURATION**

**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**

**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**

**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 3. Load Circuit and Voltage Waveforms

Product Folder Links: *SN54AHC16244 SN74AHC16244*

9 Detailed Description

9.1 Overview

The SNx4AHC16244 devices are 16-bit buffers and line drivers designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. They provide true outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pull-up resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. The SN54AHC16244 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74AHC16244 is characterized for operation from –40°C to 85°C.

9.2 Functional Block Diagram
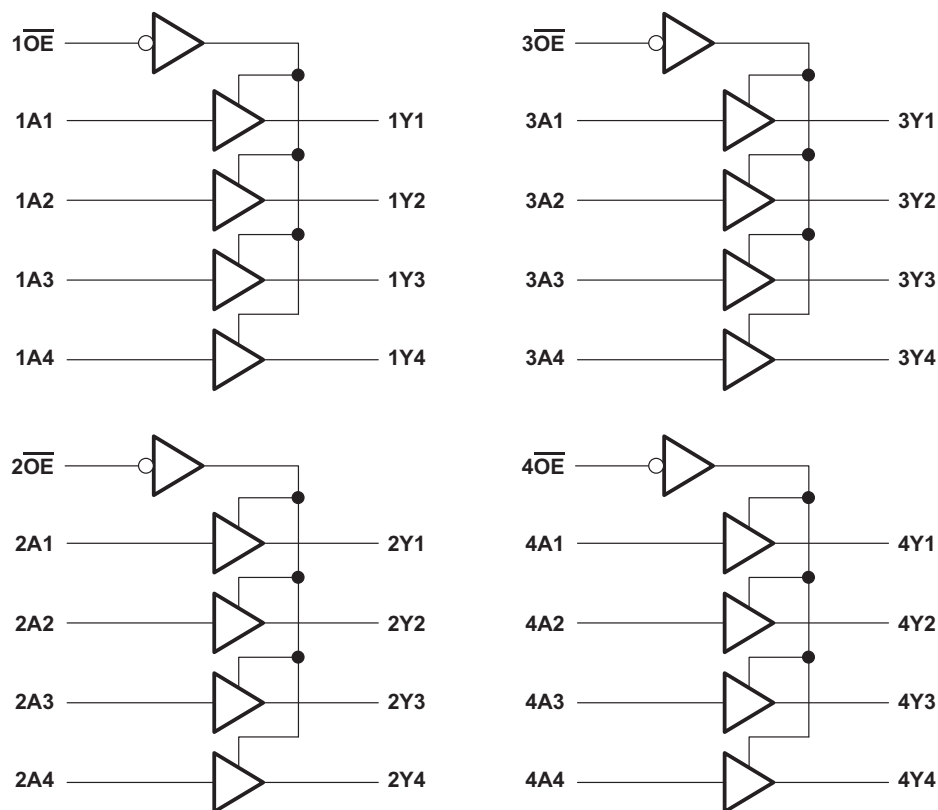
Figure 4. Logic Diagram (Positive Logic)

Product Folder Links: *SN54AHC16244 SN74AHC16244*

Functional Block Diagram (continued)
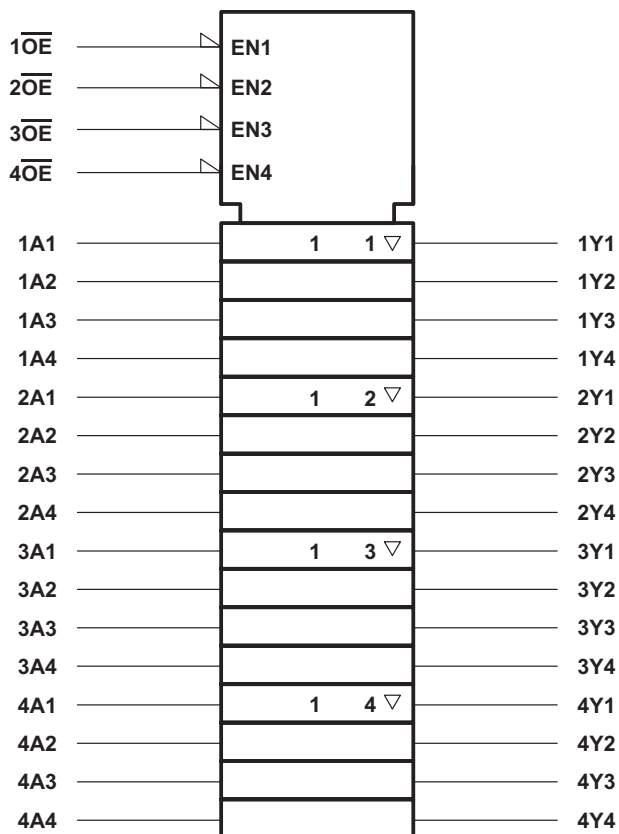
This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Figure 5. Logic Symbol

9.3 Feature Description

- Wide operating voltage range
  - Operates from 2 V to 5.5 V
- Allows down voltage translation
  - Inputs accept voltages up to 5.5 V
- Slows edges rates, minimizing output ringing

9.4 Device Functional Modes

**Table 1. Function Table
(Each 4-bit Buffer/Driver)**

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	High-Z

10 Application and Implementation

> **NOTE**
>
> Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

The SN74AHC16244 is a low-drive CMOS device that can be used for a multitude of applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs are tolerant to 5.5 V at any valid V_{CC}. This feature makes it ideal for translating down to the V_{CC} level. Figure 6 shows the reduction in ringing compared to higher-drive parts, such as AC.

10.2 Typical Application
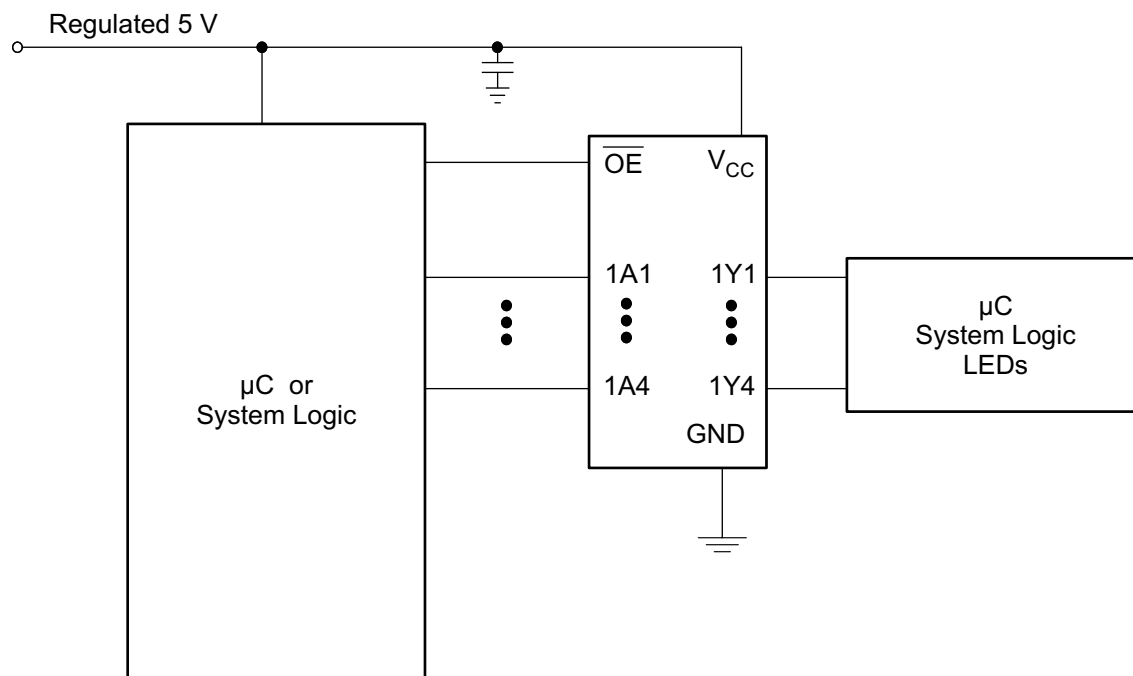
Figure 6. Application Diagram

10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

1. Recommended input conditions:
   – For rise time and fall time specifications, see (Δt/ΔV) in the *Recommended Operating Conditions* table.
   – For specified high and low levels, see (V_{IH} and V_{IL}) in the *Recommended Operating Conditions* table.
   – Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid $V_{CC.}$
2. Recommend output conditions:
   – Load currents should not exceed 25 mA per output and 75 mA total for the part.
   – Outputs should not be pulled above $V_{CC.}$

Product Folder Links: *SN54AHC16244 SN74AHC16244*

Typical Application (continued)

10.2.3 Application Curves
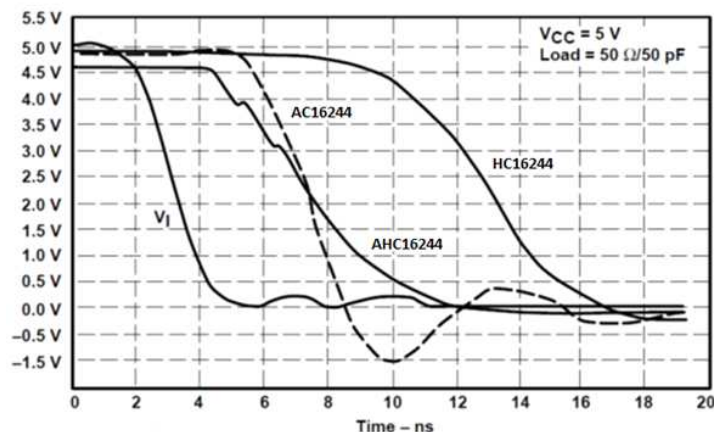
Figure 7. Switching Characteristics Comparison

11 Power Supply Recommendations

The power supply can be any voltage between the Min and Max supply voltage rating located in the *Recommended Operating Conditions*.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1 µF capacitor is recommended. If there are multiple V_{CC} terminals then 0.01 µF or 0.022 µF capacitors are recommended for each power terminal. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1 µF and 1.0 µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

12 Layout

12.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified in Figure 8 are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC}, whichever makes more sense or is more convenient. It is generally acceptable to float outputs unless the part is a transceiver.

12.2 Layout Example
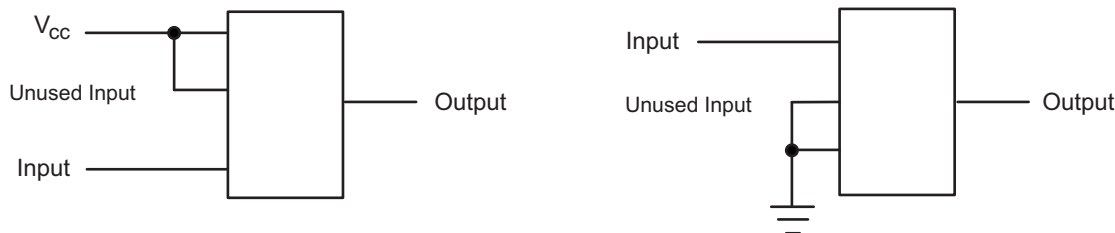
Figure 8. Layout Diagram

13 Device and Documentation Support

13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AHC16244	Click here	Click here	Click here	Click here	Click here
SN74AHC16244	Click here	Click here	Click here	Click here	Click here

13.2 Trademarks

Widebus is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

13.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74AHC16244DGGRG4	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC16244
SN74AHC16244DGGR	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC16244
SN74AHC16244DGGR.A	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC16244
SN74AHC16244DGVR	Active	Production	TVSOP (DGV) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HE244
SN74AHC16244DGVR.A	Active	Production	TVSOP (DGV) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HE244
SN74AHC16244DL	Obsolete	Production	SSOP (DL) | 48	-	-	Call TI	Call TI	-40 to 125	AHC16244
SN74AHC16244DLR	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC16244
SN74AHC16244DLR.A	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC16244

(1) Status: For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC16244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74AHC16244DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AHC16244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS
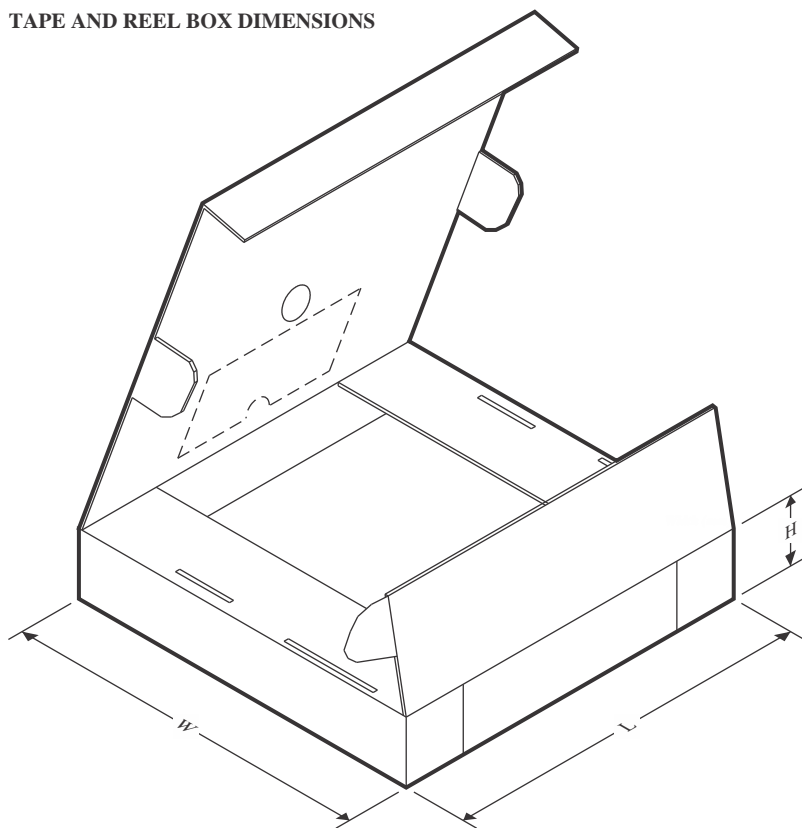
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC16244DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74AHC16244DGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74AHC16244DLR	SSOP	DL	48	1000	356.0	356.0	53.0

DL (R−PDSO−G48) PLASTIC SMALL−OUTLINE PACKAGE

0.025 (0,635)

0.0135 (0,343)
0.008 (0,203)

⊕ 0.005 (0,13) Ⓜ

48   25

0.420 (10,67)
0.395 (10,03)

0.299 (7,59)
0.291 (7,39)

0.010 (0,25)
0.005 (0,13)

Gage Plane

0.010 (0,25)

1   24

0°−8°

0.630 (16,00)
0.620 (15,75)

0.040 (1,02)
0.020 (0,51)

0.110 (2,79) MAX   0.008 (0,20) MIN

Seating Plane

△ 0.004 (0,10)

4040048−3/F   05/13
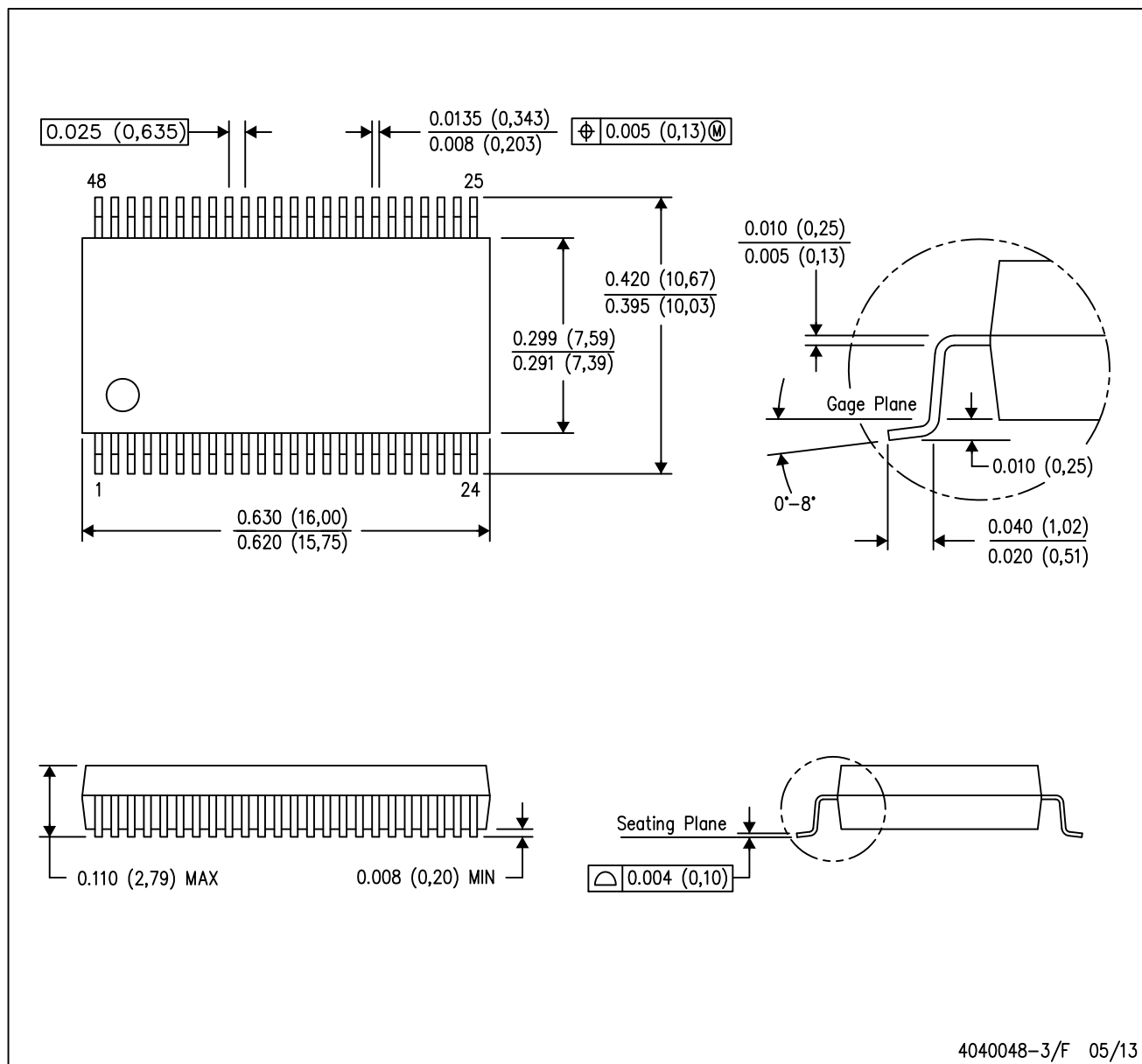
NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
        D. Falls within JEDEC MO−118

PowerPAD is a trademark of Texas Instruments.

DGV (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN
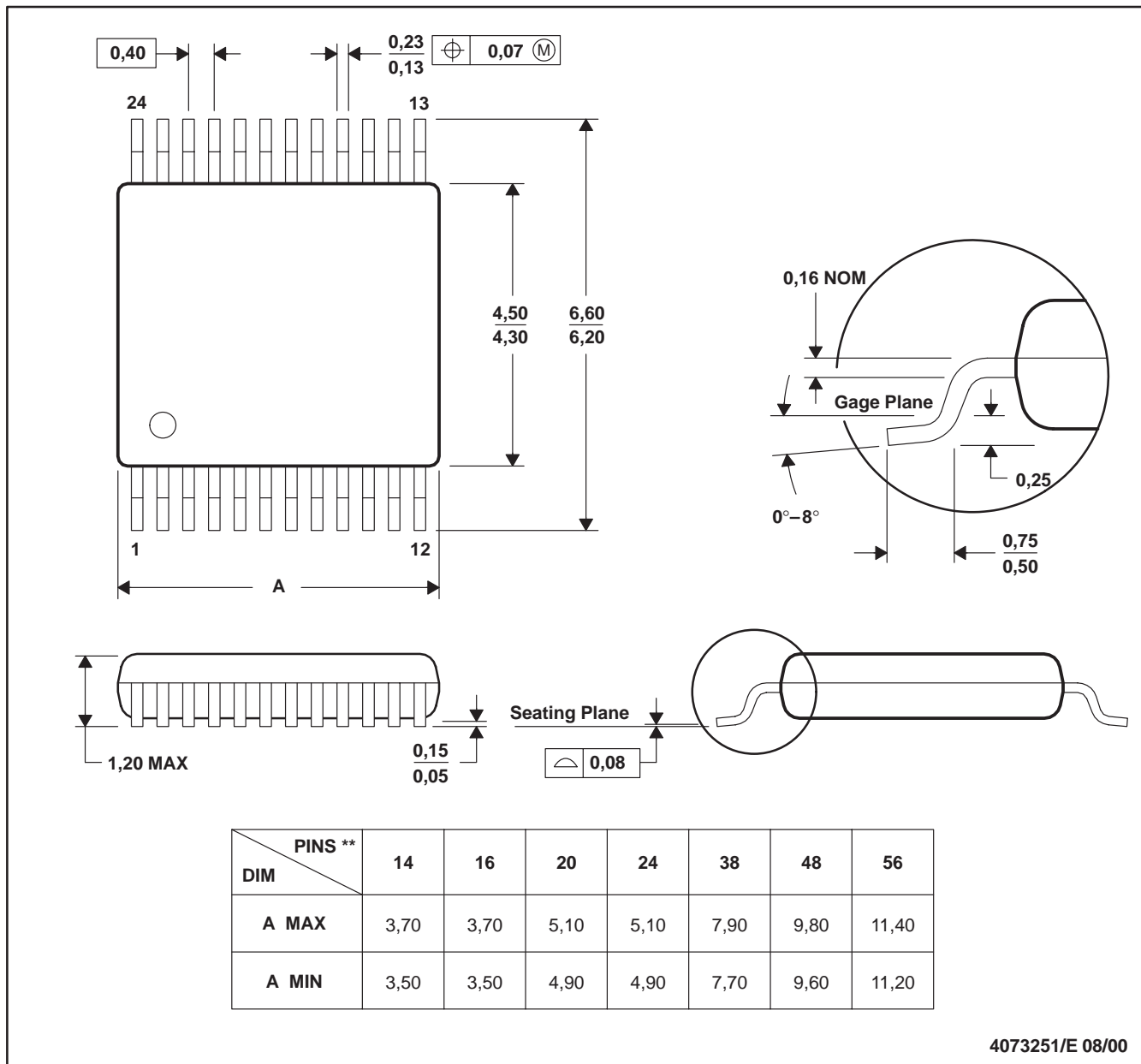
PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A.   All linear dimensions are in millimeters.
B.   This drawing is subject to change without notice.
C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D.   Falls within JEDEC: 24/48 Pins – MO-153
                  14/16/20/56 Pins – MO-194

![Texas Instruments logo] **TEXAS INSTRUMENTS**

8.3
7.9 TYP

PIN 1 ID
AREA

A

1

46X 0.5

48

2X
11.5

12.6
12.4
NOTE 3

24

25

48X 0.27
0.17

B

6.2
6.0

⊕ 0.08 Ⓜ C A B

C

SEATING PLANE

⌒ 0.1 C

1.2
1.0

(0.15) TYP

SEE DETAIL A

0.25

GAGE PLANE

0° - 8°

0.75
0.50

0.15
0.05

DETAIL A
TYPICAL
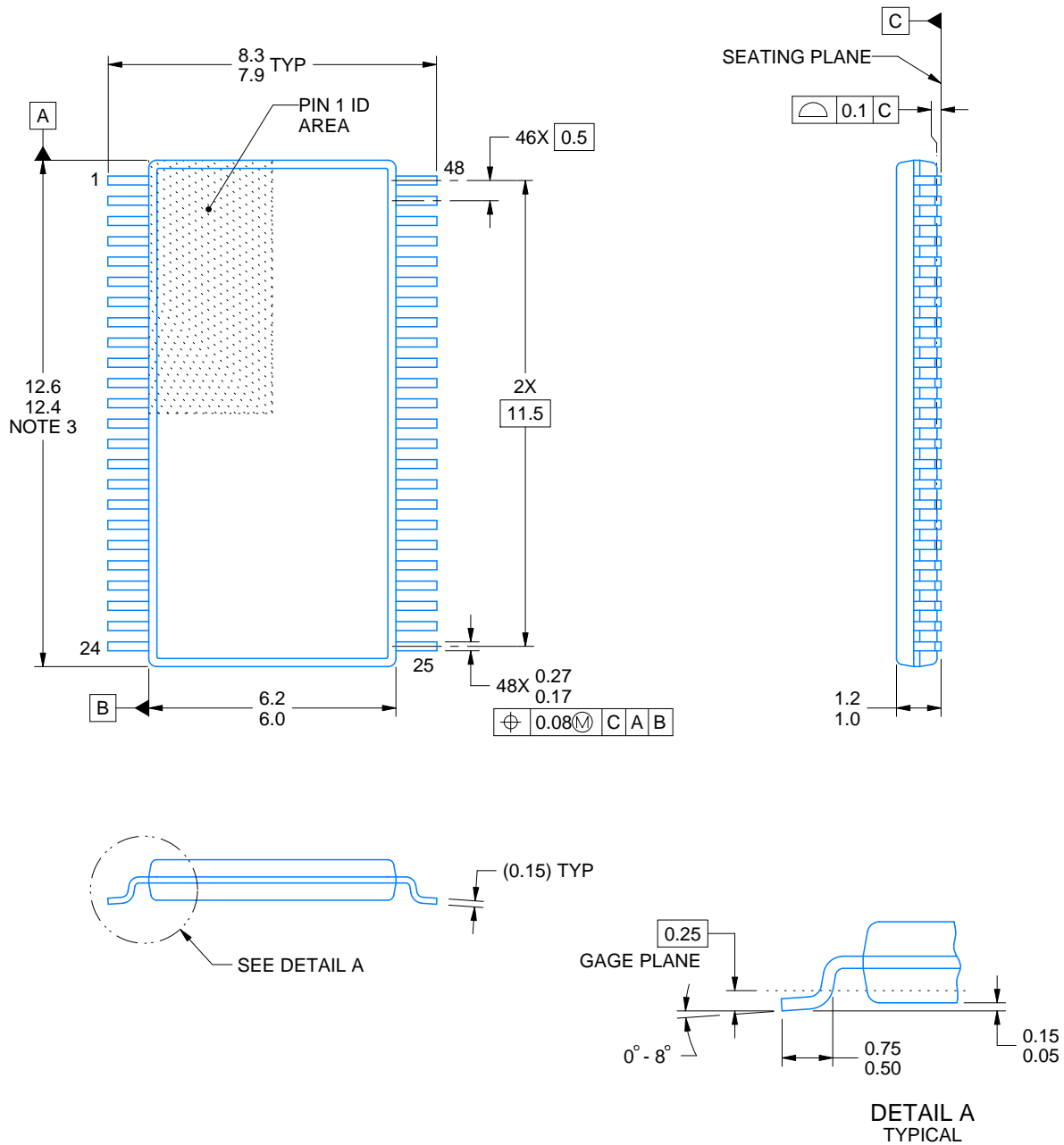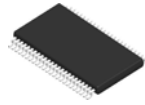
4214859/B   11/2020

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

TEXAS
INSTRUMENTS
www.ti.com

48X (1.5)

SYMM

1

48X (0.3)

48

46X (0.5)

(R0.05)
TYP

SYMM

24

25

(7.5)
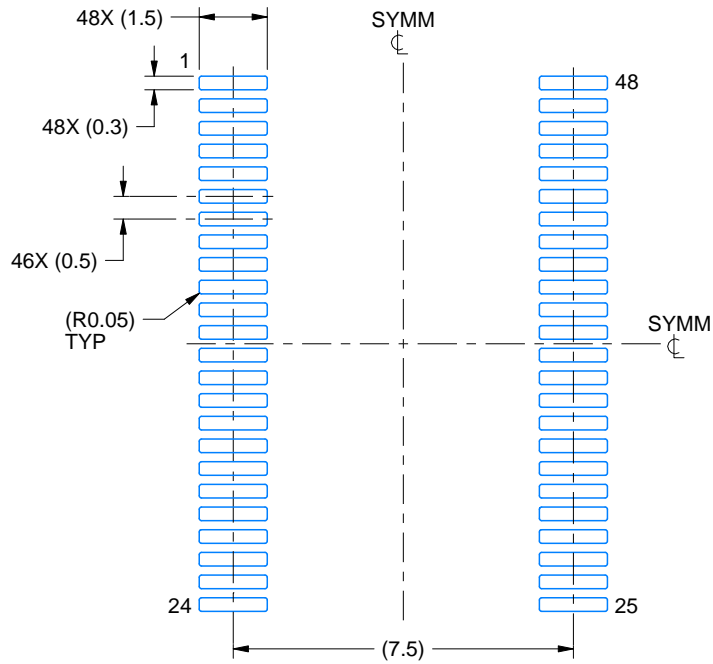
LAND PATTERN EXAMPLE
SCALE:6X

SOLDER MASK
OPENING

METAL

0.05 MAX
ALL AROUND

NON SOLDER MASK
DEFINED

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

0.05 MIN
ALL AROUND

SOLDER MASK
DEFINED
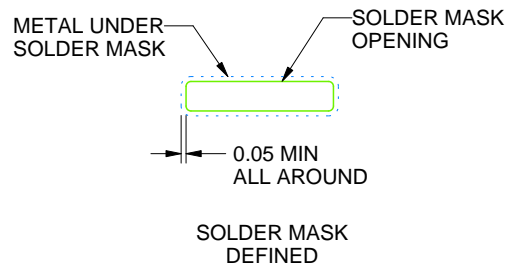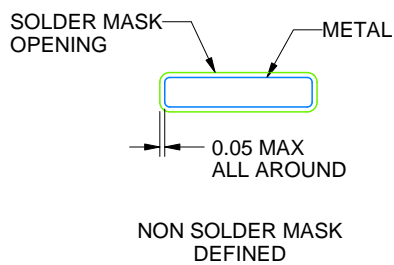
SOLDER MASK DETAILS

4214859/B   11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

48X (1.5)

1

48X (0.3)

46X (0.5)

(R0.05) TYP

SYMM

SYMM

48

25

24

(7.5)
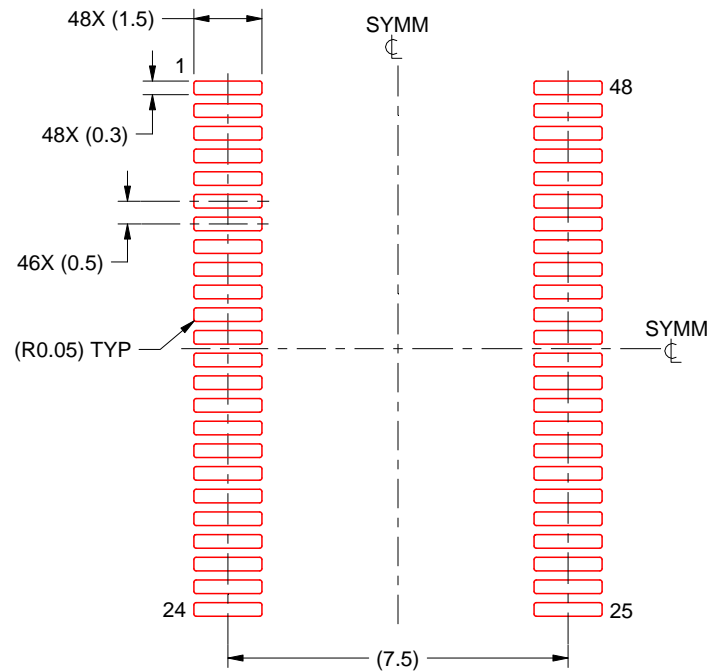
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B   11/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN
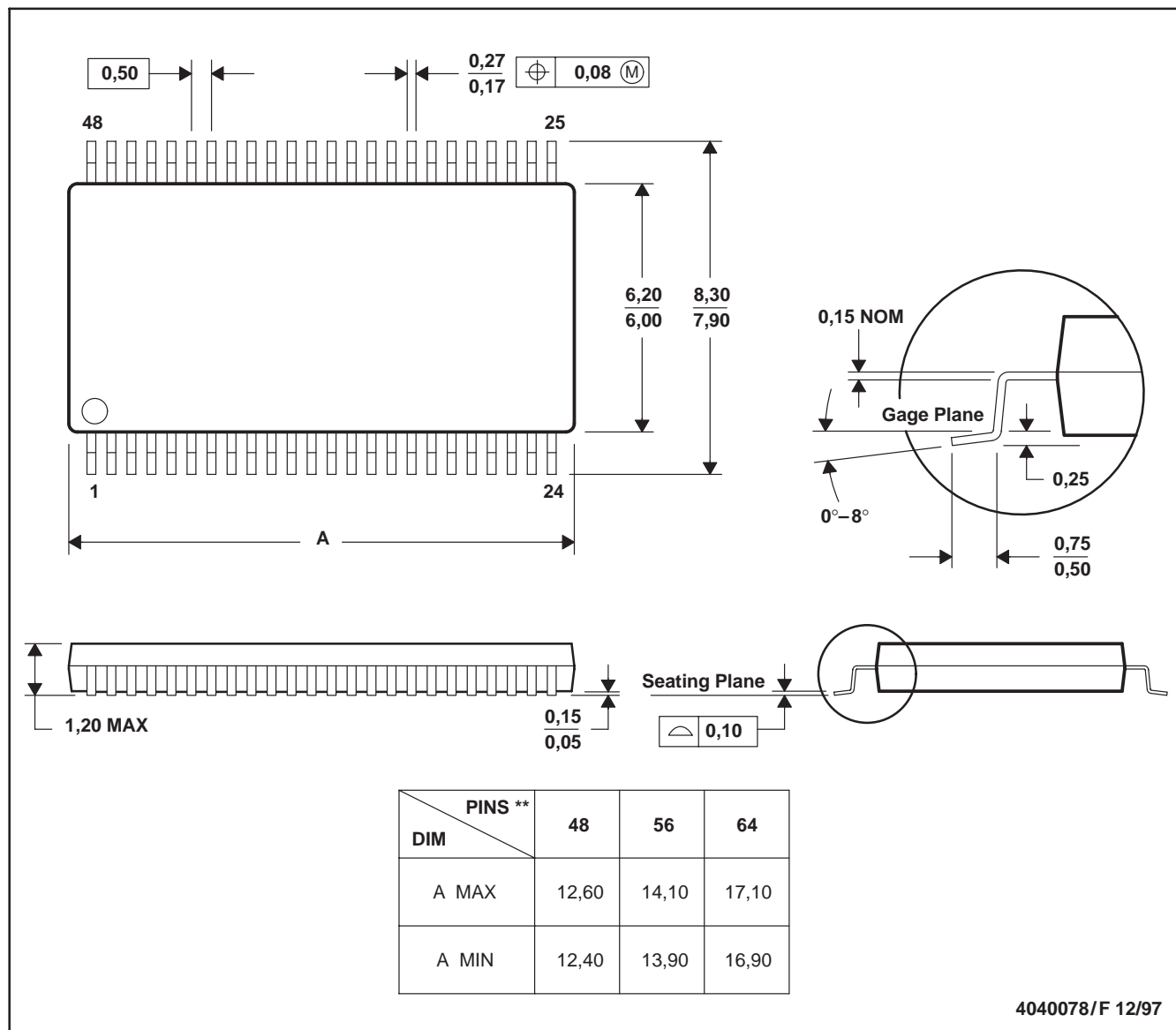
PINS **	48	56	64
DIM			
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078 / F 12/97

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold protrusion not to exceed 0,15.
         D. Falls within JEDEC MO-153

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

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